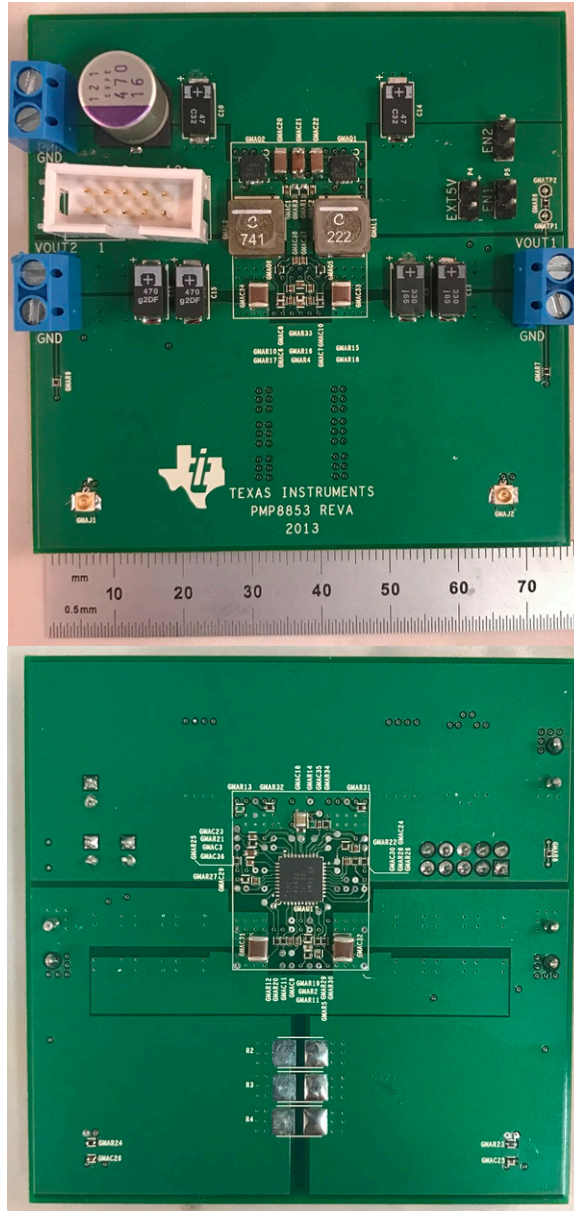


Photo of the prototype



1 Startup and shutdown

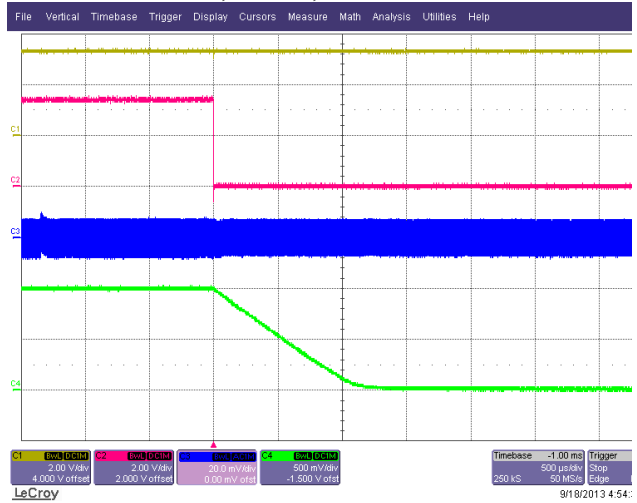
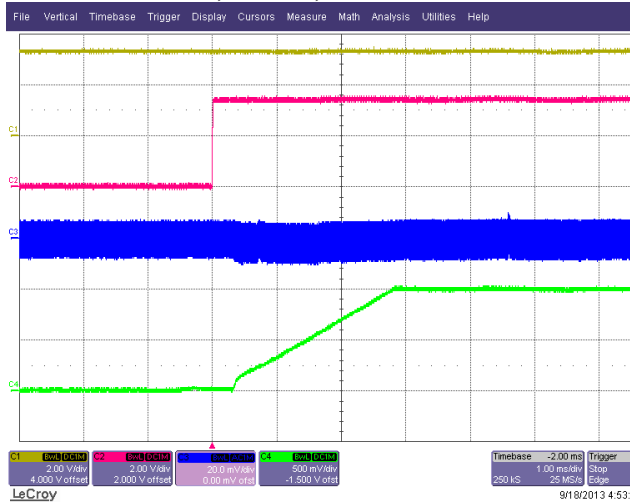
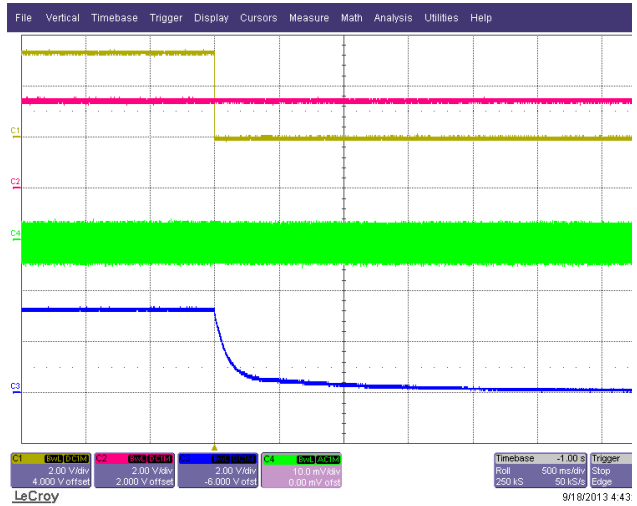
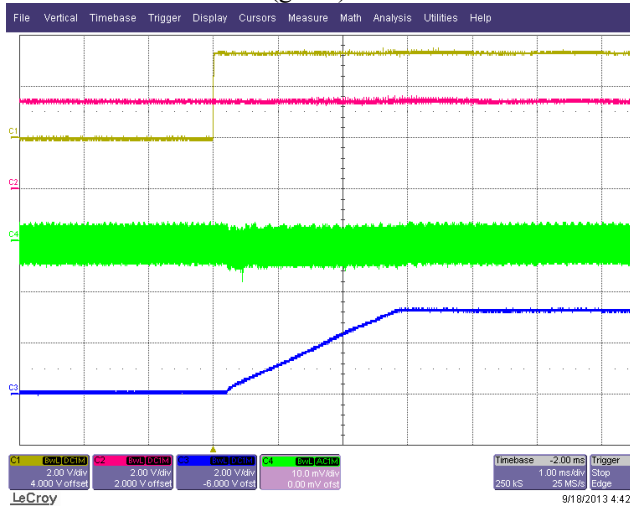
Ch1 is VOUT1=3.3V and Ch2 is VOUT2=1V.

Trace C1: EN1 (yellow)

Trace C2: EN2 (red)

Trace C3: VOUT1 (blue)

Trace C4: VOUT2 (green)



2 Output Ripple

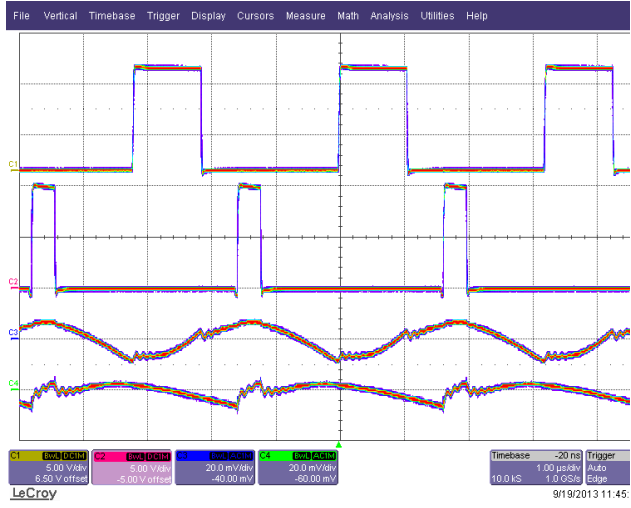
Ch1 is VOUT1=3.3V and Ch2 is VOUT2=1V.

Trace C1: VSW1

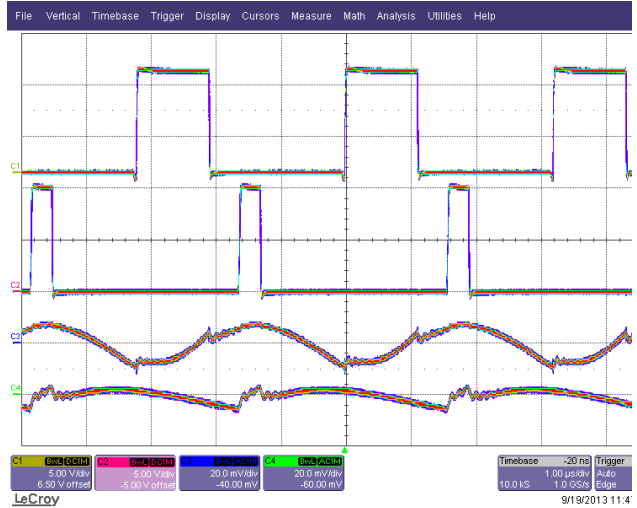
Trace C2: VSW2

Trace C3: VOUT1

Trace C4: VOUT2

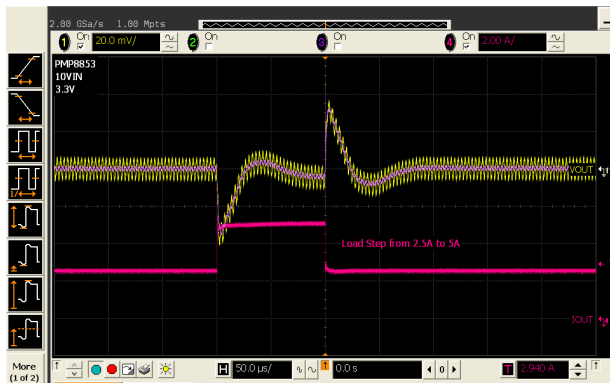


LeCroy
10VIN, Ch1 = 3.3V/0.8A, Ch2 = 1.0V/10A (2x 100uF, 6.3V, 1210+2x470uF, 4V, 10mohm, 7343), VOUT1=20mVpp

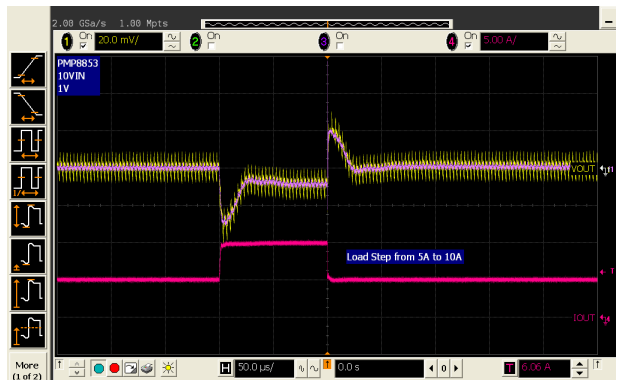


LeCroy
10VIN, Ch1 = 3.3V/8A, Ch2 = 1.0V/1A (2x 100uF, 6.3V, 1210+2x330uF, 6.3V, 9mohm, 7343), VOUT2=10mVpp

3 Transient



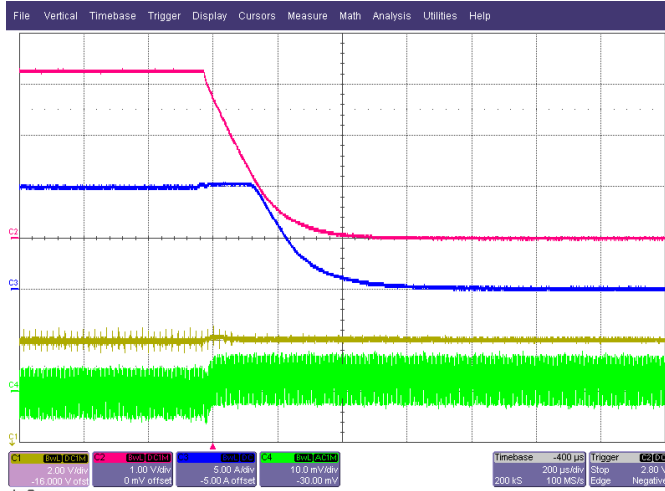
10VIN, 3.3V/2.5A->5A->2.5A (-35mV/+30mV)



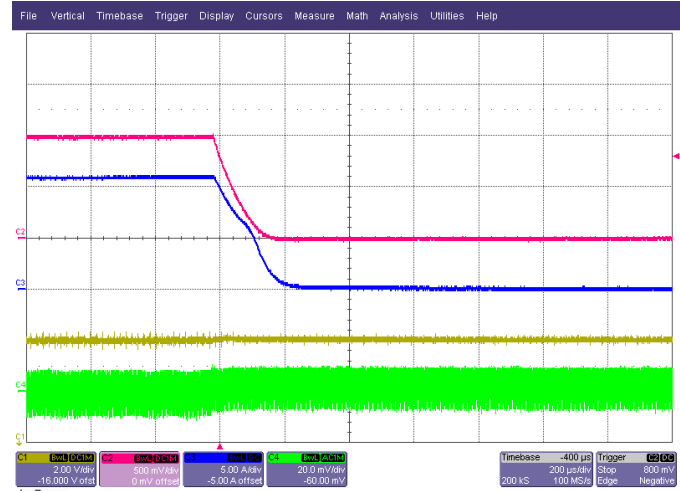
10VIN, 1V/5A->10A->5A (-30mV/+20mV)

4 Over-Current protection

- Ch1 is VOUT1=3.3V and Ch2 is VOUT2=1V.
- Trace C1: VIN (yellow)
- Trace C2: VOUT of channel under test (red)
- Trace C3: IOUT (blue)
- Trace C4: VOUT of other channel (green)



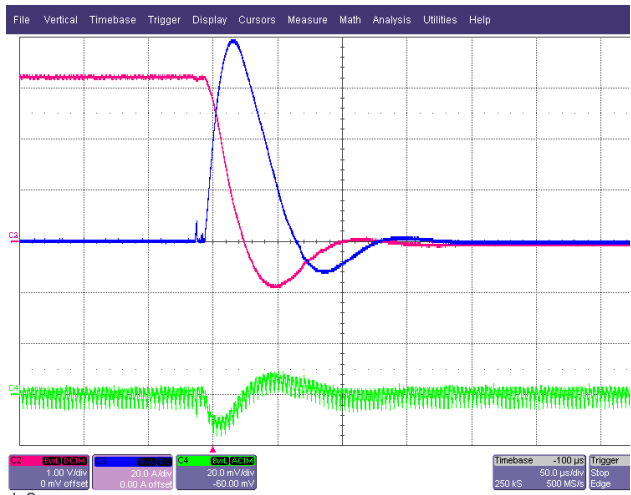
12Vin, Ch1 load regulation and over-current protection, Ch2=1V/5A



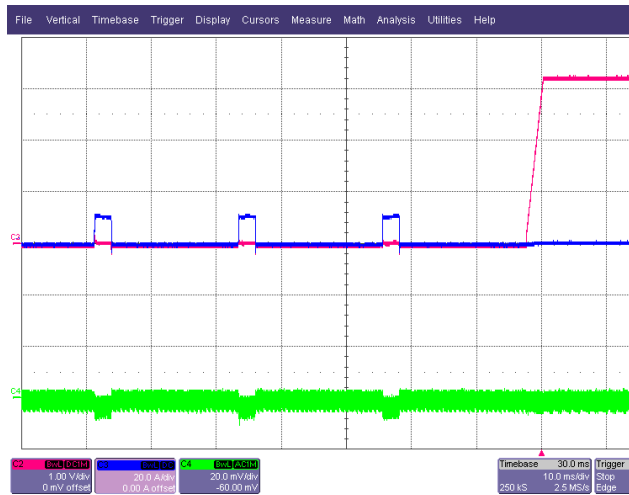
12Vin, Ch2 load regulation and over-current protection, Ch1 =3.3V/4A

5 Short-Circuit Protection

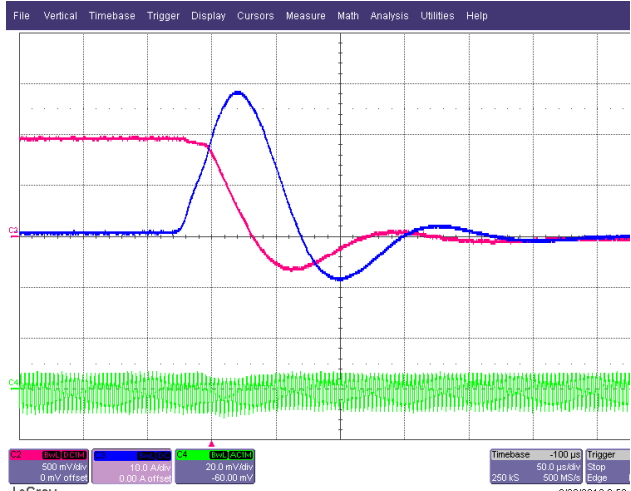
Ch1 is VOUT1=3.3V and Ch2 is VOUT2=1V.
Trace C2: VOUT of channel under test (red)
Trace C3: IOUT (blue)
Trace C4: VOUT of other channel (green)



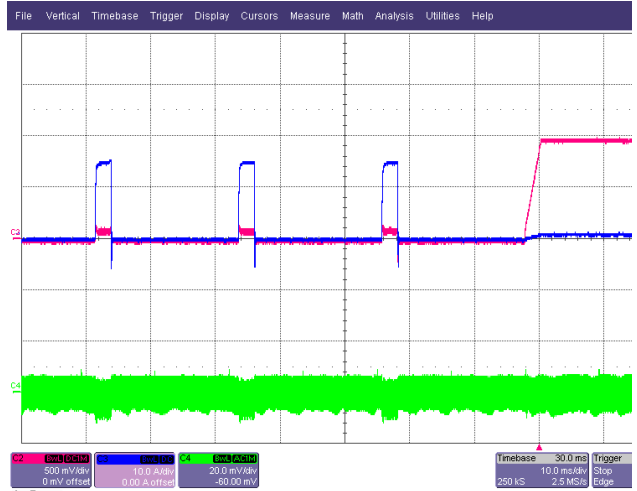
12Vin, Ch1, Short circuit applied



12Vin, Ch1, Short circuit released

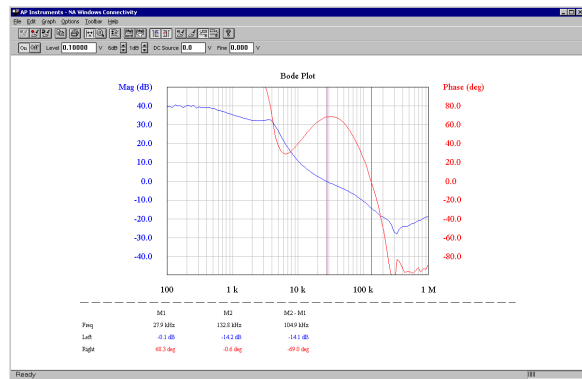


12Vin, Ch2, Short circuit applied

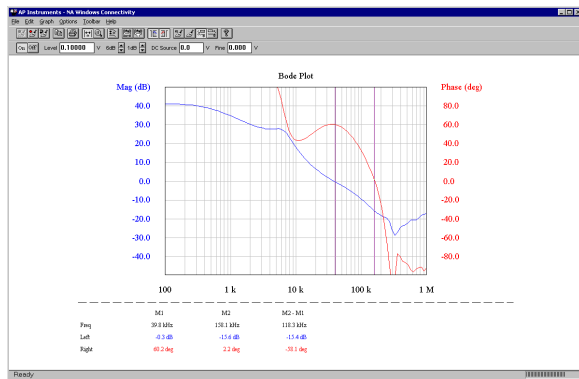


12Vin, Ch2, Short circuit released

6 Bode Plot

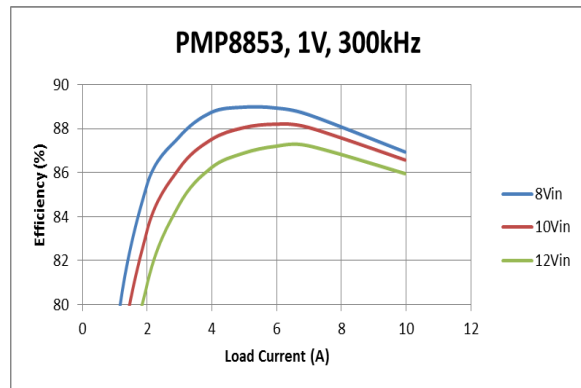


VIN=10V, VOUT1=3.3V/5A (BW=27.9kHz, PM=68.3D)

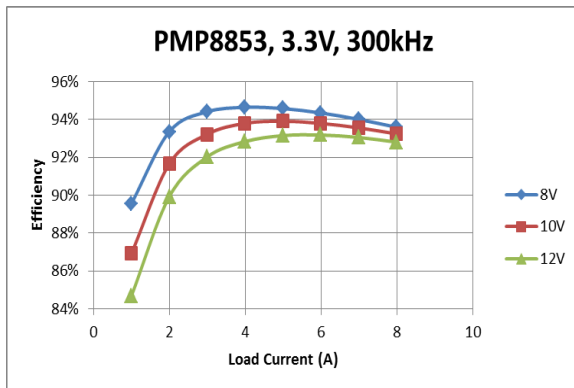


VIN=10V, VOUT2=1V/10A (BW=39.8kHz, PM=60.2D)

7 Efficiency



1V efficiency @300kHz



3.3V efficiency @300kHz

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